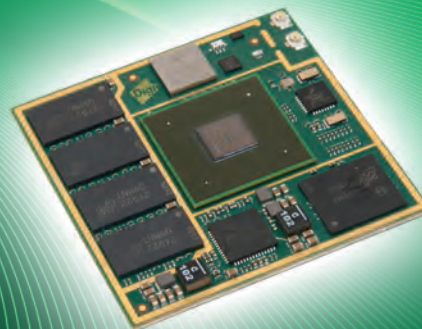


ConnectCore[®] 6

Scalable High-Performance System-on-Module

Freescale i.MX6 based surface-mount module solution with scalable, single-/multi-core performance and integrated wireless.



Overview

The ConnectCore 6 is an ultra-compact and highly integrated system-on-module solution based on the Freescale i.MX6 Cortex-A9 processor family.

With processor speeds up to 1.2 GHz and fully pin-compatible single-/dual-/quad-core variants, the ConnectCore 6 offers a truly future-proof platform solution with scalable performance and pre-certified wireless 802.11a/b/g/n and Bluetooth 4.0, including Bluetooth Low Energy, connectivity.

Its low-profile, surface-mount design maximizes integration flexibility and significantly reduces design risk in a highly cost-effective, reliable form factor with optimized heat dissipation capabilities even in the most demanding quad-core system configurations.

Integrated cloud integration as part of the Digi Linux and Android software platform support offers secure remote management and web services capabilities through the scalable Device Cloud by Etherios[™].

Key Applications



Medical/Healthcare/Wellness



Transportation

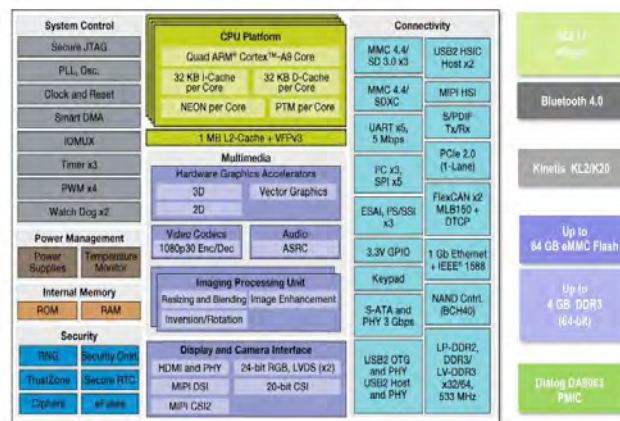


Industrial



Supported Software Platforms

Application Highlight



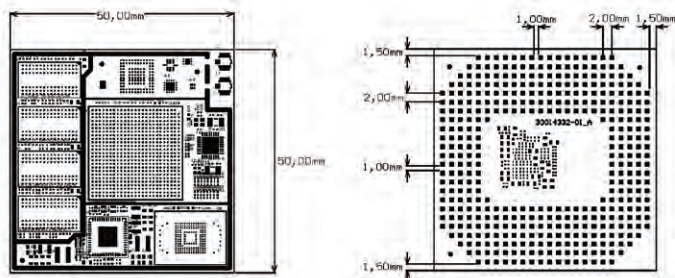
Features/Benefits

- Scalable Cortex-A9 multi-core performance
- Independent Cortex-M0+/Cortex-M4 Microcontroller Assist[™] subsystem
- Cost-effective, reliable, low-profile surface-mount module form factor
- Pre-certified 802.11a/b/g/n and Bluetooth 4.0
- Smart Power Management Architecture with high-efficiency PMIC
- Android, Yocto Project Linux and Windows Embedded Compact software platform support
- Seamless cloud integration through Device Cloud by Etherios[™]
- Reliable design with IEC 60068 and HALT verification
- Designed for long-term availability



Specifications ConnectCore® 6	
Application Processor	Freescale i.MX6Solo/DualLite/Dual/Quad with up to four Cortex-A9 cores Industrial (850 MHz), Extended and Commercial (1/1.2 GHz) i.MX6 variants "32 KB I-Cache/32 KB D-Cache, up to 1 MB L2-Cache"
Memory	Up to 64 GB eMMC flash, up to 2 GB DDR3 (64-bit)
PMIC	Dialog DA9063
Graphics	Multi-stream-capable HD video engine with 1080p60 decode, 1080p30 encode and 3D video playback in HD in high-performance families; Superior 3D graphics performance with up to 4 shaders at 200 Mt/s w/OpenCL support; Separate 2D and/or Vertex acceleration engines for UI support; Stereoscopic image sensor support for 3D imaging
Security	RNG, TrustZone, Ciphers, Security Cntrl, Secure RTC, Secure JTAG, eFuses (OTP)
Peripherals/Interfaces	MMC 4.4/SD 3.0 x3MMC 4.4/SDXC, UART x5 (5 Mbps), MIPI HSI, S/PDIF Tx/Rx, I2C x3, SPI x5, ESAI, I2S/SSI x3, FlexCAN x2, MLB150 + DTC, S-ATA and PHY (3 Gbps), USB2 OTG and PHY, USB 2.0 Host and PHY, USB 2.0 HSIC Host x2, PWM, 3.3V GPIO, Keypad, PCIe 2.0 (x1 lane), HDMI and PHY, MIPI DSI, MIPI CSI2, 20-bit CSI, 24-bit RGB, LVDS (x2), RTC, External address/data bus, Watchdog, Timers, JTAG
External Bus	26-bit address / up to 32-bit data (multiplexed and non-multiplexed modes)
Ethernet	1 Gbit Ethernet + IEEE 1588 (MII10, MII100, RMII, RGMII)
Wi-Fi	802.11a/b/g/n: 2.412 - 2.484 GHz, 4.900 - 5.850 GHz 802.11b: 1, 2, 5.5, 11 Mbps (17 dBm typical ± 2 dBm) 802.11a/g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps (15 dBm typical ± 2 dBm) 802.11n: 15, 30, 45, 60, 90, 120, 135, 150 Mbps (12 dBm typical ± 2 dBm) HT40, MCS 0-7 Security: WEP, WPA-PSK/WPA2-Personal, WPA/WPA2 Enterprise, 802.11i, Access Point Mode (up to 10 clients), Wi-Fi Direct Industry Certifications: Wi-Fi Alliance Logo Certification Ready, CCXv4 ASD Ready
Bluetooth	Profiles: GAP, SPP, HSP, HFP, FTP, PAN, OPP, HID, A2DP, AVRCP, HDP
On-Module Microcontroller Assist	Kinetis KL2 (Cortex-M0+); MKL26Z128VFT4/MKL26Z64VFT4/MKL2632VFT4 or Kinetis K20 (Cortex-M4); MK20DN32VFT5/MK20DX32VFT5/MK20DN64VFT5/MK20DX64VFT5/ MK20DN128VFT5/MK20DX128VFT5 Independent subsystem with interconnect to i.MX6 via SPI
Operating Temperature (Tj)	Industrial: -40° C to +105° C; Extended Commercial: -20° C to +105° C / Commercial: 0° C to +95° C
Storage Temperature	Storage Temperature -50° C to +125° C (-58° F to +257° F)
Relative Humidity	Relative Humidity 5% to 90% (non-condensing)
Altitude	Altitude 12,000 feet (3,658 meters)
Radio Approvals*	US, Canada, EU, Japan, Australia/New Zealand
Emissions / Immunity / Safety*	FCC Part 15 Class B, EN 55022 Class B, EN 61000-3-2, EN 61000-3-3, ICES-003 Class B, VCCI Class II, AS 3548, FCC Part 15 Subpart C Section 15.247, IC (Industry Canada), RSS-210 Issue 5 Section 6.2.2(o), EN 300 328, EN 301 489-17, EN 55024, EN 301 489-3, Safety UL/UR (or equivalent)
Design Verification*	Temperature: IEC 60068-2-1, IEC 60068-2-2, IEC 60068-2-78 Vibration/Shock: IEC 60068-2-6, IEC 60068-2-64, IEC 60068-2-27, HALT
Mechanical Dimensions	LGA-400, 2 mm pitch

* Pending



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info@digi.com

